

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows:

Claims 1-5 (cancelled)

6. (Original) A semiconductor chip having a plurality of chip connection portions formed on a surface thereof,

wherein the plurality of chip connection portions are arranged in positions standardized among a plurality of predetermined types of semiconductor chips.

7. (Original) A semiconductor chip as claimed in claim 6,

wherein the plurality of predetermined types of semiconductor chips have identical functions but are of different grades.

8. (New) A semiconductor chip having, on a surface thereof, a chip connection region that fits any of a plurality of predetermined types of semiconductor chips,

wherein, in the chip connection region, chip connection portions are formed in standardized positions so as to fit any of the plurality of predetermined types of semiconductor chips, and the chip connection portions are arranged along an edge of the chip connection region, and

wherein the chip connection region is rectangular in shape, and the chip connection portions are arranged along opposite sides of the chip connection region.

9. (New) The semiconductor chip having a plurality of chip connection portions formed on a surface thereof,